

Product Change Notification

Change Title	Power IC and Thermal sensor Substituting PCB-assembly Adoption - v1	Date	2022/06/20	PCN No	F2215-1
PCN level:	Major				
Models:	CFexpress 3TE6; PCIe M.2 P42 3TE6/3IE6, PCIe M.2 P80 3TE6/3IE6				
Category:	Hardware - PCB				

Description:

Due to **shortage of power ICs and thermal sensor**, Innodisk will adopt substituting PCB-assembly into our BOMs.

Product families affected are listed in following table with implementation dates.

This PCN will affect all part numbers including standard and customized ones.

Model Name	Current Part Number
PCIe M.2 P42 3IE6	DHM24-%DD%
PCIe M.2 P80 3TE6	DEM28-%DD%
CFexpress 3TE6	D%CFX%DD%
PCIe M.2 P42 3TE6	DEM24-%DD%
PCIe M.2 P80 3IE6	DHM28-%DD%

Summary of Change

Adopt substituting PCB-assembly with new power ICs and thermal sensor into our BOMs.

1. Add substituting material RICHTEK RT5753 and ADI 3309 for Power IC TI TPS62827DMQR.
2. Add substituting material Novosense NST112-DSTR for thermal sensor Microchip MCP98244T-BE/MNY.

Key Milestone Dates

Effective Date: 2022/07/22

*Milestone dates are subject to change based on business and operational conditions.

Customer Impact of Change and Recommended Action:

Innodisk anticipates no negative impact to customer's application.

There is no functional implication to customer's application but improve reliability, and qualification of these changes may not be necessary.


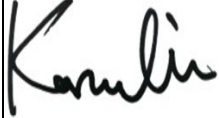

Notes:

No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones.

Innodisk apologizes for any inconvenience caused by this and appreciate your understanding.

Innodisk promises that new items deliver quality and reliability for your application. If you have any further inquiry of our products or if you have any question about the specification of it, please contact Innodisk sales person.

Thank you for your confidence in Innodisk in the past and looking forward to serving you in the near future.

CC WU, Vice President Product Planning Dept. 	KAREN LIN, Manager Product Planning Dept. 	DAVIS CHUANG, Section Manager Product Planning Dept. 
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